

HD74LS125A

Quadruple Bus Buffer Gates (with three-state outputs)

REJ03D0430-0200

Rev.2.00

Feb.18.2005

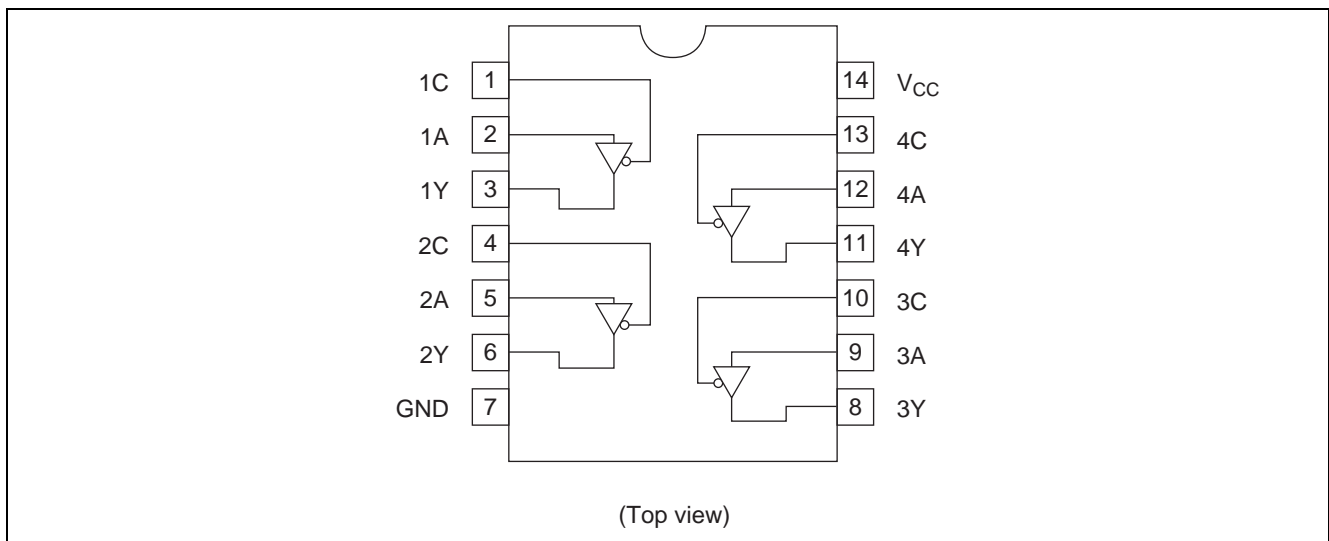
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS125AP	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS125AFPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)
HD74LS125ARPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



Function Table

Inputs		Outputs
C	A	Y
H	X	Z
L	L	L
L	H	H

Note: H ; high level,
L ; low level,
X ; irrelevant,
Z ; off (high-impedance) state of a 3-state output

Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC}	7	V
Input voltage	V_{IN}	7	V
Power dissipation	P_T	400	mW
Storage temperature	T_{stg}	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
High level output current	I_{OH}	—	—	-2.6	mA
Low level output current	I_{OL}	—	—	24	mA
Operating temperature	T_{opr}	-20	25	75	°C

Electrical Characteristics

($T_a = -20$ to $+75$ °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V_{IH}	2.0	—	—	V	
	V_{IL}	—	—	0.8	V	
Output voltage	V_{OH}	2.4	—	—	V	$V_{CC} = 4.75$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V, $I_{OH} = -2.6$ mA
	V_{OL}	—	—	0.5 0.4	V	$I_{OL} = 24$ mA $I_{OL} = 12$ mA $V_{CC} = 4.75$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V
	I_{OZ}	—	—	20 -20	μA	$V_O = 2.4$ V $V_O = 0.4$ V $V_{CC} = 5.25$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V
Input current	I_{IH}	—	—	20	μA	$V_{CC} = 5.25$ V, $V_I = 2.7$ V
	I_{IL}	—	—	-0.4	mA	$V_{CC} = 5.25$ V, $V_I = 0.4$ V
	I_I	—	—	0.1	mA	$V_{CC} = 5.25$ V, $V_I = 7$ V
Short-circuit output current	I_{OS}	-40	—	-225	mA	$V_{CC} = 5.25$ V
Supply current	I_{CC}	—	11	20	mA	$V_{CC} = 5.25$ V
Input clamp voltage	V_{IK}	—	—	-1.5	V	$V_{CC} = 4.75$ V, $I_{IN} = -18$ mA

Note: * $V_{CC} = 5$ V, $T_a = 25$ °C

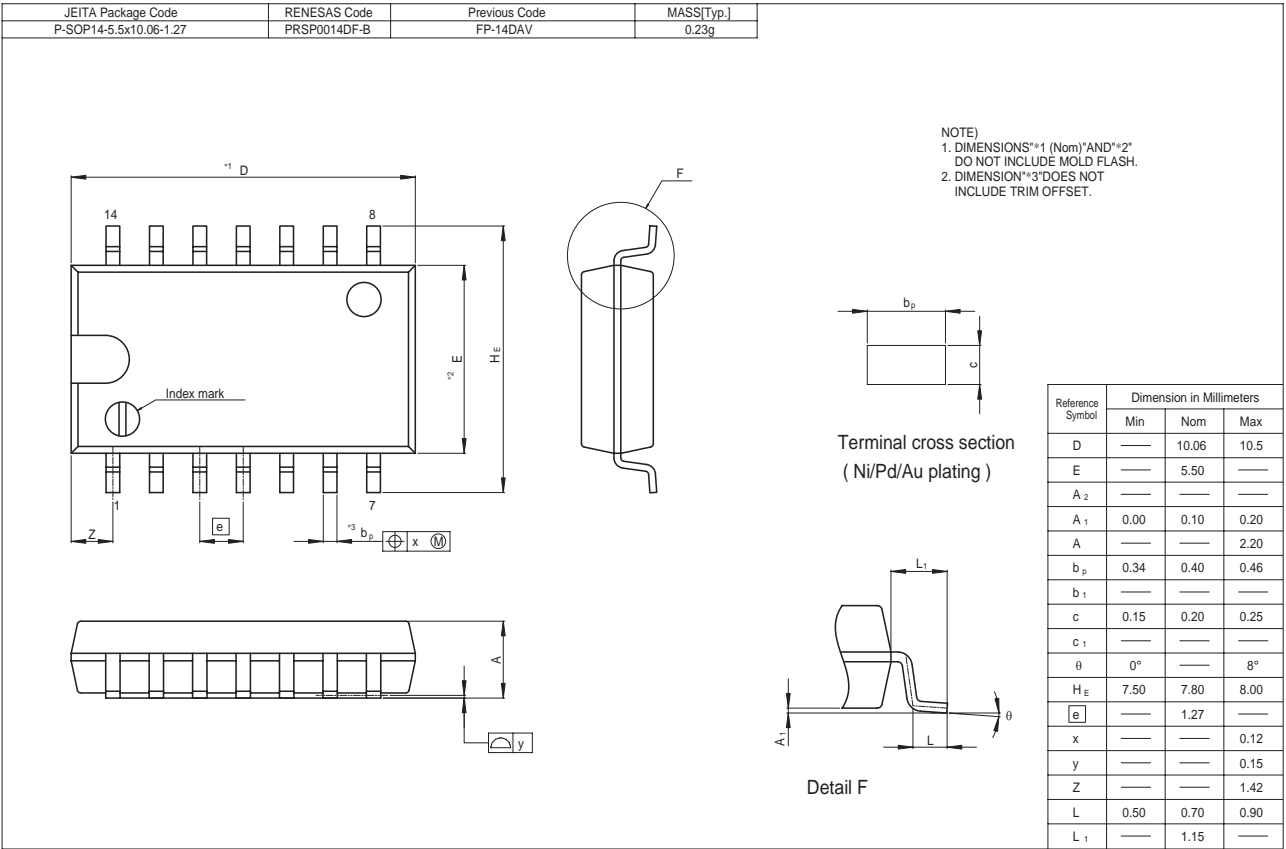
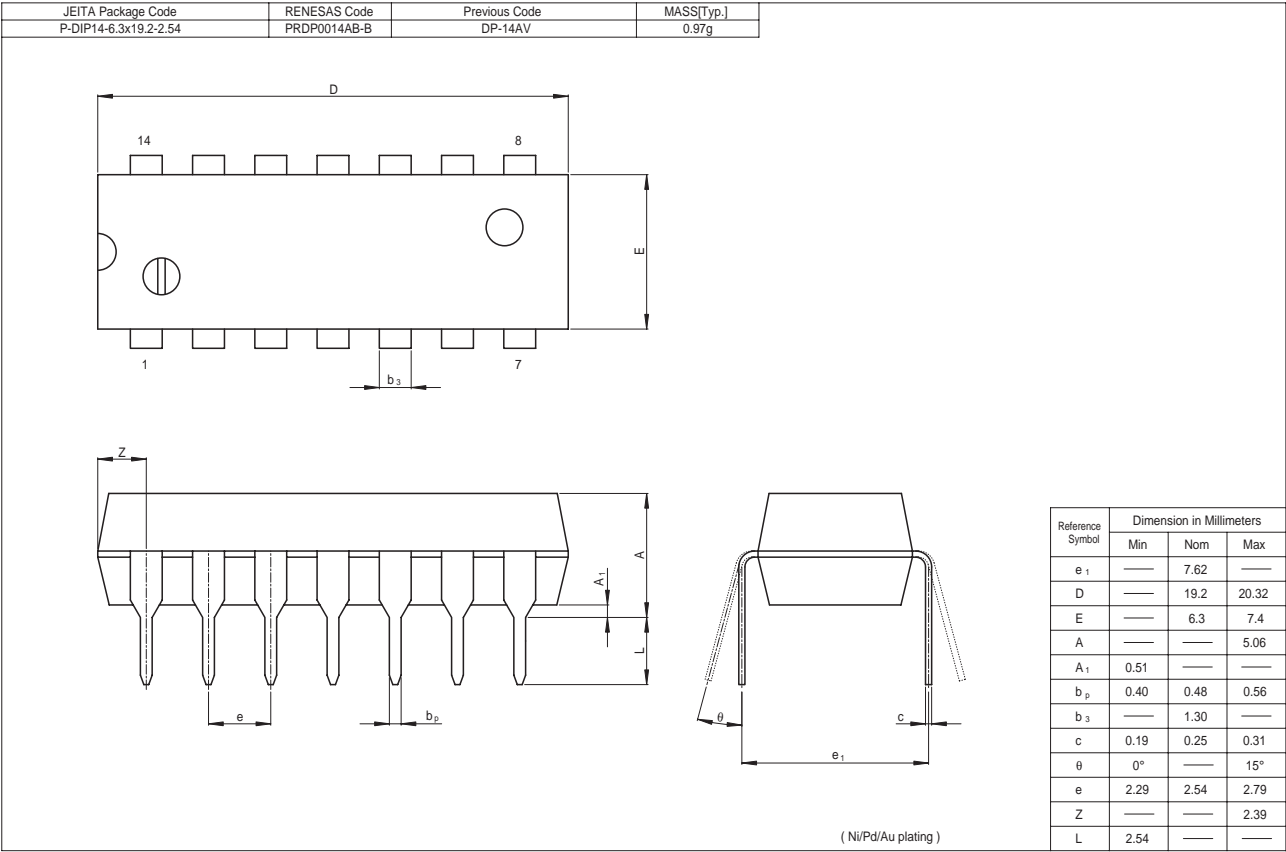
Switching Characteristics

($V_{CC} = 5$ V, $T_a = 25$ °C)

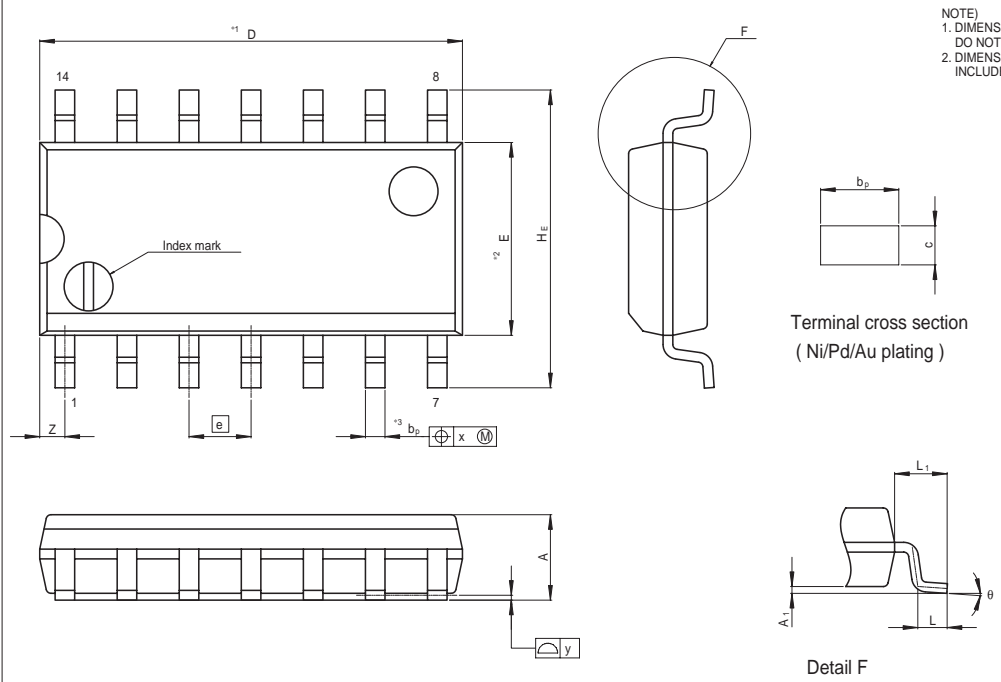
Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t_{PLH}	—	9	15	ns	$C_L = 45$ pF, $R_L = 667$ Ω
	t_{PHL}	—	7	18		
Output enable time	t_{ZH}	—	12	20		
	t_{ZL}	—	15	25		
Output disable time	t_{HZ}	—	—	20		$C_L = 5$ pF, $R_L = 667$ Ω
	t_{LZ}	—	—	20		

Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions



JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP14-3.95x8.65-1.27	PRSP0014DE-A	FP-14DNV	0.13g



NOTE)
1. DIMENSIONS*1 (Nom)*AND*2*
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION*3*DOES NOT
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	8.65	9.05
E	—	3.95	—
A ₂	—	—	—
A ₁	0.10	0.14	0.25
A	—	—	1.75
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	5.80	6.10	6.20
e	—	1.27	—
x	—	—	0.25
y	—	—	0.15
Z	—	—	0.635
L	0.40	0.60	1.27
L ₁	—	1.08	—

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